

SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

SDLS003

D2632, JANUARY 1981 — REVISED MARCH 1988

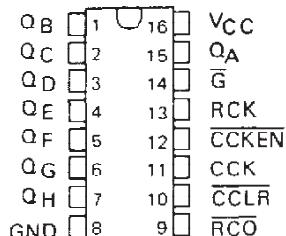
- 8-Bit Counter with Register
- Parallel Register Outputs
- Choice of 3-State ('LS590) or Open-Collector ('LS591) Register Outputs
- Guaranteed Counter Frequency:
DC to 20 MHz

description

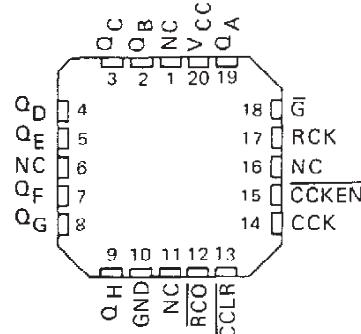
These devices each contain an 8-bit binary counter that feeds an 8-bit storage register. The storage register has parallel outputs. Separate clocks are provided for both the binary counter and storage register. The binary counter features a direct clear input \bar{CCLR} and a count enable input $CCKEN$. For cascading, a ripple carry output RCO is provided. Expansion is easily accomplished for two stages by connecting RCO of the first stage to CCK of the second stage. Cascading for larger count chains can be accomplished by connecting RCO of each stage to CCK of the following stage.

Both the counter and register clocks are positive-edge triggered. If the user wishes to connect both clocks together, the counter state will always be one count ahead of the register. Internal circuitry prevents clocking from the clock enable.

SN54LS590, SN54LS591 . . . J OR W PACKAGE
SN74LS590, SN74LS591 . . . N PACKAGE
(TOP VIEW)

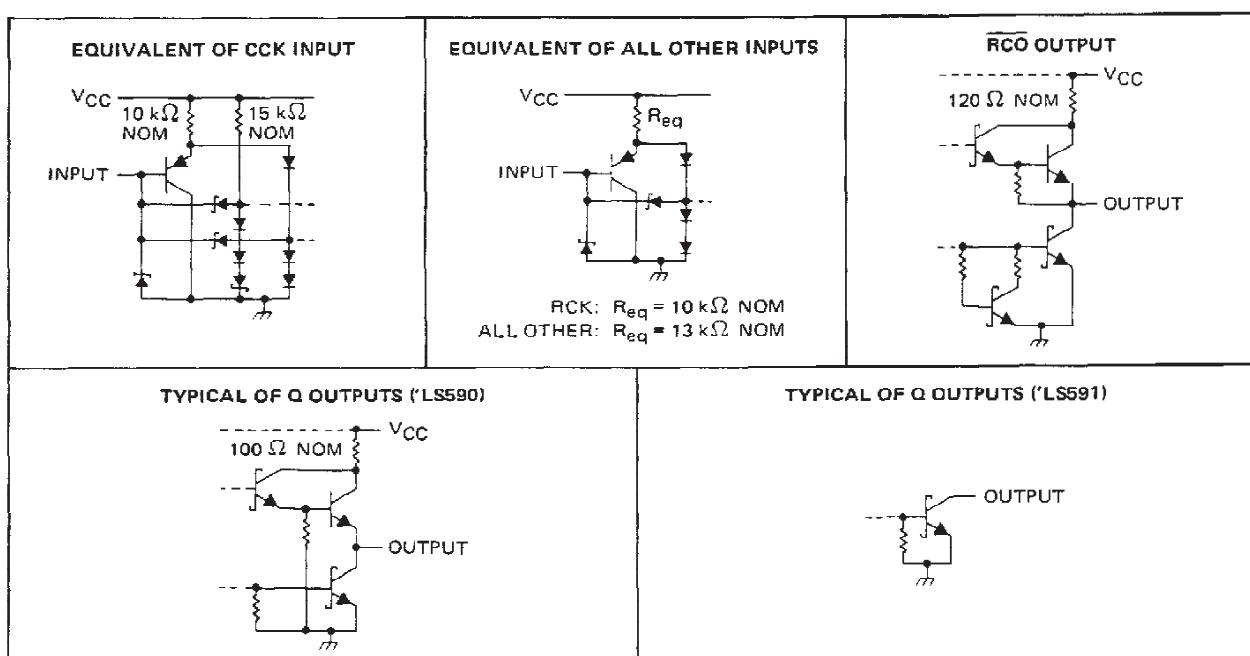


SN54LS590, SN54LS591 . . . FK PACKAGE
(TOP VIEW)



schematics of inputs and outputs

NC — No internal connection



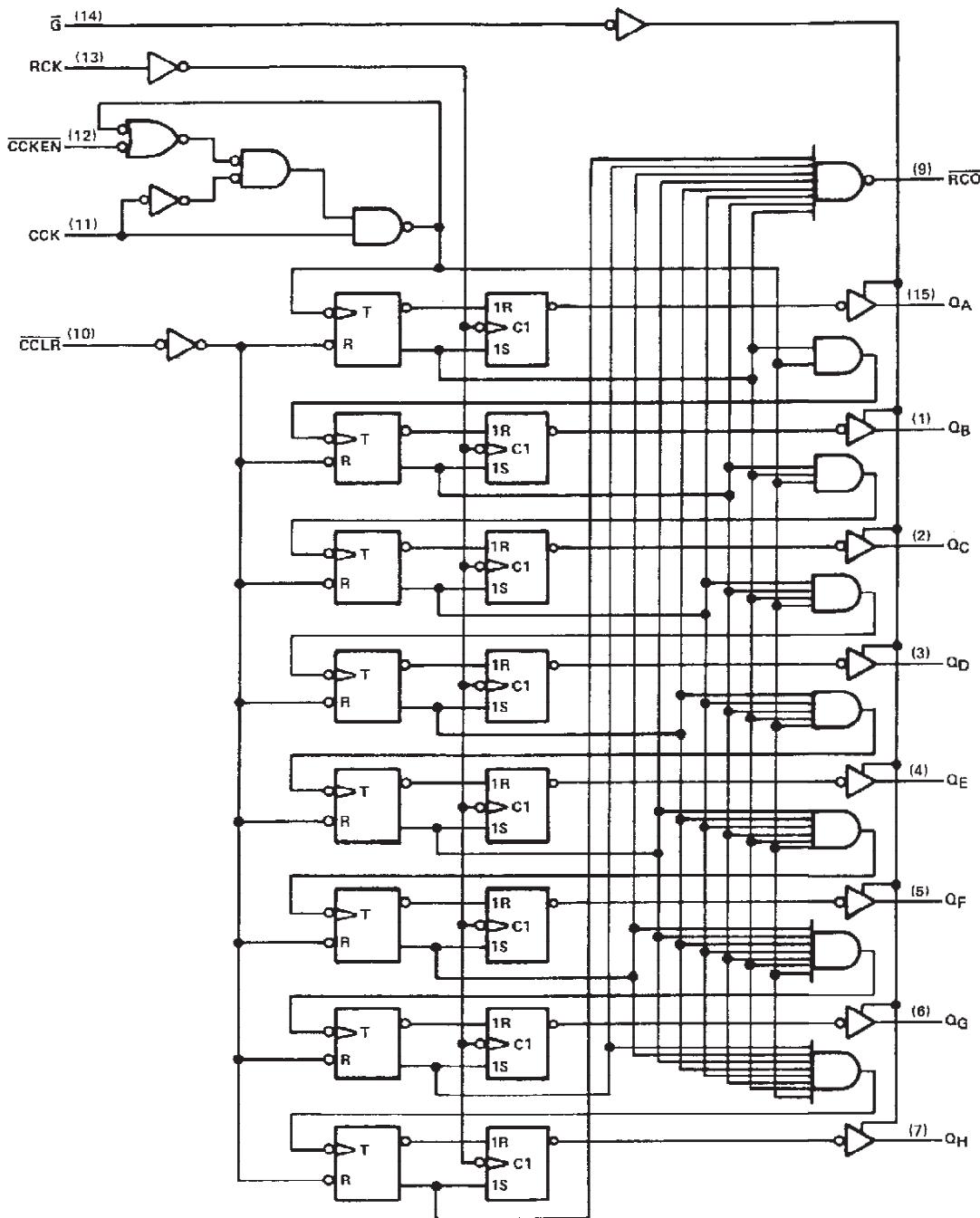
PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

logic diagram (positive logic)



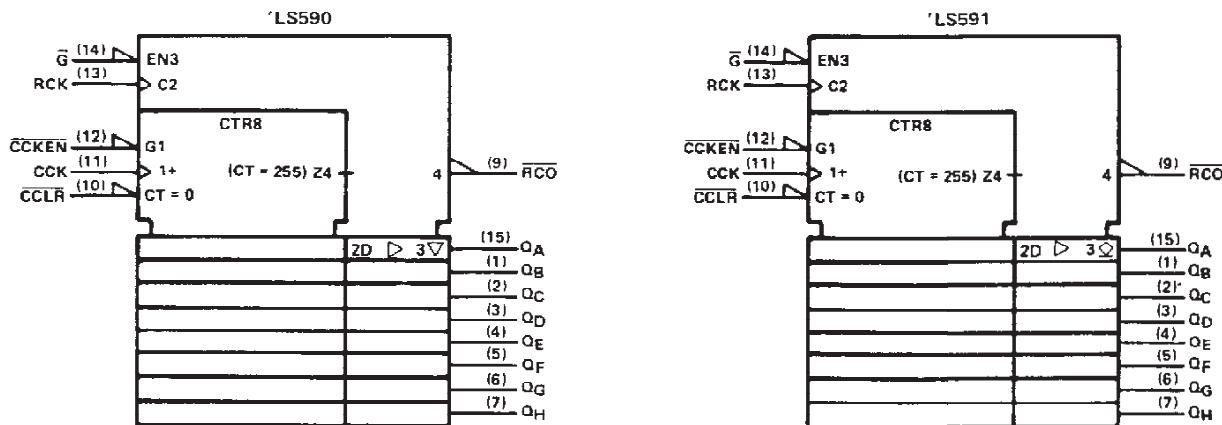
Pin numbers shown are for J, N and W packages.



POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

logic symbols[†]



[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for J, N, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage	7 V
Off-state output voltage	5.5 V
Operating free-air temperature range: SN54LS590, SN54LS591	-55°C to 125°C
SN74LS590, SN74LS591	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

		SN54LS'			SN74LS'			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.7			0.8	V
V _{OH}	High-level output voltage	Q, 'LS591 only			5.5			V
I _{OH}	High-level output current	RCO		-1			-1	mA
		Q, 'LS590 only		-1			-2.6	
I _{OL}	Low-level output current	RCO		8			16	mA
		Q		12			24	
f _{CCK}	Counter clock frequency	0	20	0	0	20	20	MHz
f _{RCK}	Register clock frequency	0	25	0	0	25	25	MHz
t _{w(CCK)}	Duration of counter clock pulse	25			25			ns
t _{w(CCLR)}	Duration of counter clear pulse	20			20			ns
t _{w(RCK)}	Duration of register clock pulse	20			20			ns
t _{su}	Setup time	CCKEN low before CCK↑	20		20			ns
		CCLR inactive before CCK↑	20		20			
		CCK before RCK↑ (see Note 2)	40		40			
t _h	Hold time	CCKEN low after CCK↑	0		0			ns
T _A	Operating free-air temperature	-55	125	0	0	70		°C

NOTE 2: This setup time ensures the register will see stable data from the counter outputs. The clocks may be tied together in which case the register state will be one clock pulse behind the counter.

TEXAS
INSTRUMENTS

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SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS [†]			SN54LS [‡]			SN74LS [‡]			UNIT		
					MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX			
V _{IK}		V _{CC} = MIN, I _I = -18 mA			-1.5			-1.5			V		
V _{OH}	'LS590 Q		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX	I _{OH} = -1 mA	2.4	3.2		2.4	3.1	3.2	V		
	RCO			I _{OH} = -2.6 mA									
	'LS591 Q			I _{OH} = -1 mA	2.4	3.2							
I _{OH}	'LS591 Q		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX	V _{OH} = 5.5 V,	0.1			0.1			mA		
V _{OL}	Q		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX	I _{OL} = 12 mA	0.25	0.4		0.25	0.4	0.5	V		
	RCO			I _{OL} = 24 mA									
	Q			I _{OL} = 8 mA	0.25	0.4							
	RCO			I _{OL} = 16 mA									
I _{OZH}	'LS590 Q		V _{CC} = MAX, V _{IH} = 2 V, V _{IL} = MAX, V _O = 2.7 V		20			20			μA		
I _{OZL}	'LS590 Q		V _{CC} = MAX, V _{IH} = 2 V, V _{IL} = MAX, V _O = 0.4 V		-20			-20			μA		
I _I	V _I		V _{CC} = MAX, V _I = 7 V		0.1			0.1			mA		
I _{IH}	V _I		V _{CC} = MAX, V _I = 2.7 V		20			20			μA		
I _{IL}	CCK		V _{CC} = MAX, V _I = 0.4 V		-0.8			-0.8			mA		
	All others				-0.2			-0.2			mA		
I _{OS} [§]	'LS590 Q		V _{CC} = MAX, V _O = 0 V		30	130	-30	130			mA		
	RCO				-20	100	-20	100			mA		
I _{CC}	'LS590	I _{CCH}	V _{CC} = MAX, All possible inputs grounded, All outputs open		33	55	33	55			mA		
		I _{CCL}			44	65	44	65					
		I _{CCZ}			46	65	46	65					
	'LS591	I _{CCH}			35	55	35	55					
		I _{CCL}			42	65	42	65					

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C

[§] Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS590			'LS591			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
f _{max}	RCK	Q	R _L = 667 Ω, C _L = 45 pF	20	35		20	35		MHz
t _{PLH}	CCK↑	RCO			14	22		16	24	ns
t _{PHL}	CCK↑	RCO	R _L = 1 kΩ, C _L = 30 pF		20	30		25	38	ns
t _{PLH}	CCLR↑	RCO			30	45		32	48	ns
t _{PLH}	RCK↑	Q			12	18		25	38	ns
t _{PHL}	RCK↑	Q	R _L = 667 Ω, C _L = 45 pF		22	33		28	42	ns
t _{PZH}	̄G↑	Q			25	38				ns
t _{PZL}	̄G↑	Q			30	45				ns
t _{PHZ}	̄G↑	Q	R _L = 667 Ω, C _L = 5 pF		20	30				ns
t _{PLZ}	̄G↑	Q			25	38				ns
t _{PLH}	̄G↑	Q						34	50	ns
t _{PHL}	̄G↑	Q	R _L = 667 Ω, C _L = 45 pF					32	48	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-87517012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8751701EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8751701EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8751701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-8751701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74LS590D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590N3	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SN74LS590N3	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SN74LS590NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS590FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS590FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS590W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS590W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

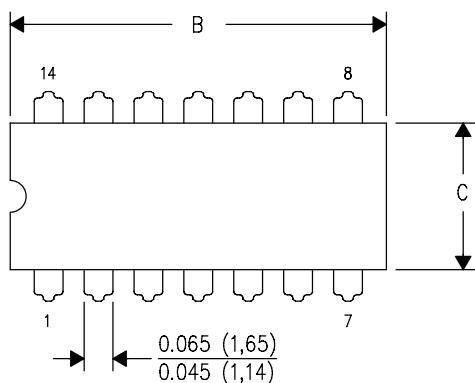
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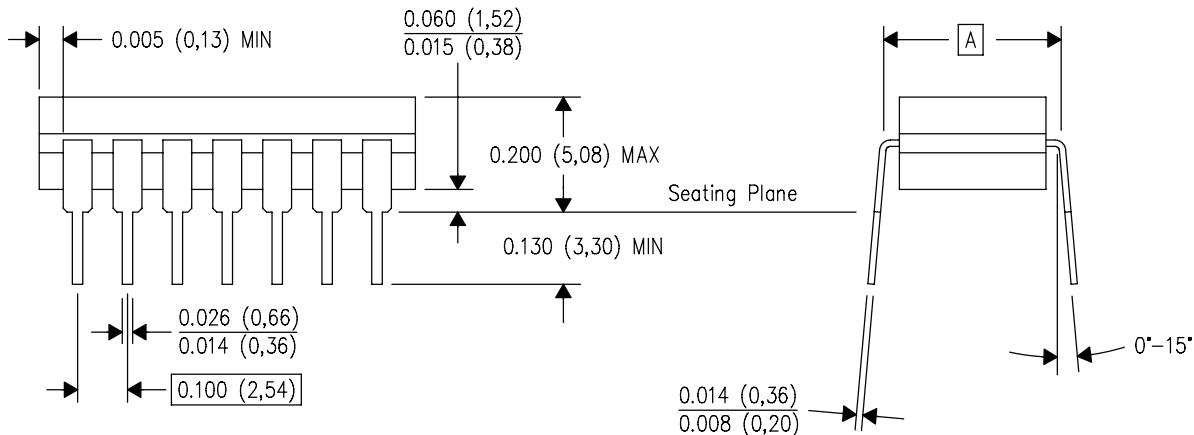
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

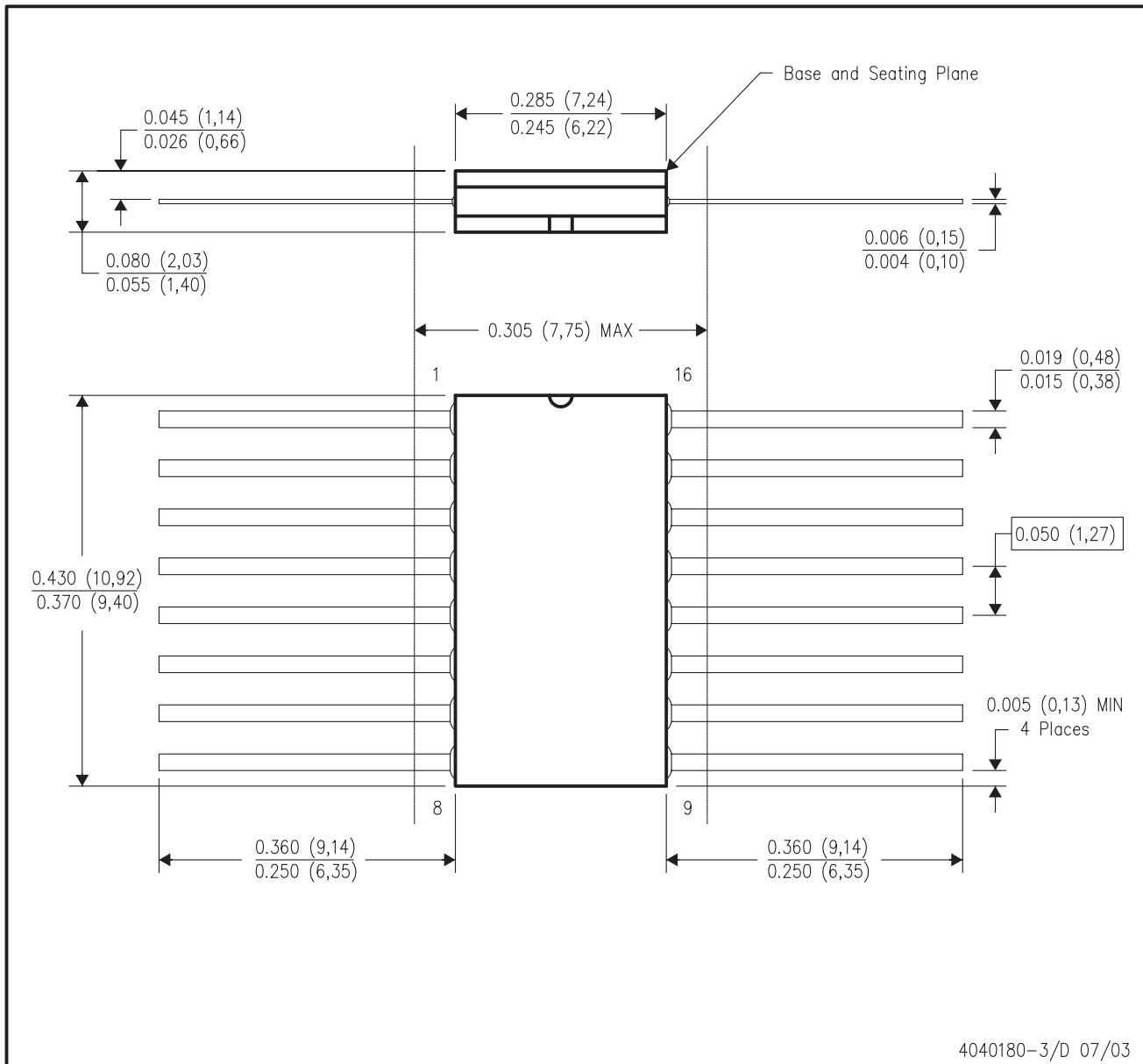


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



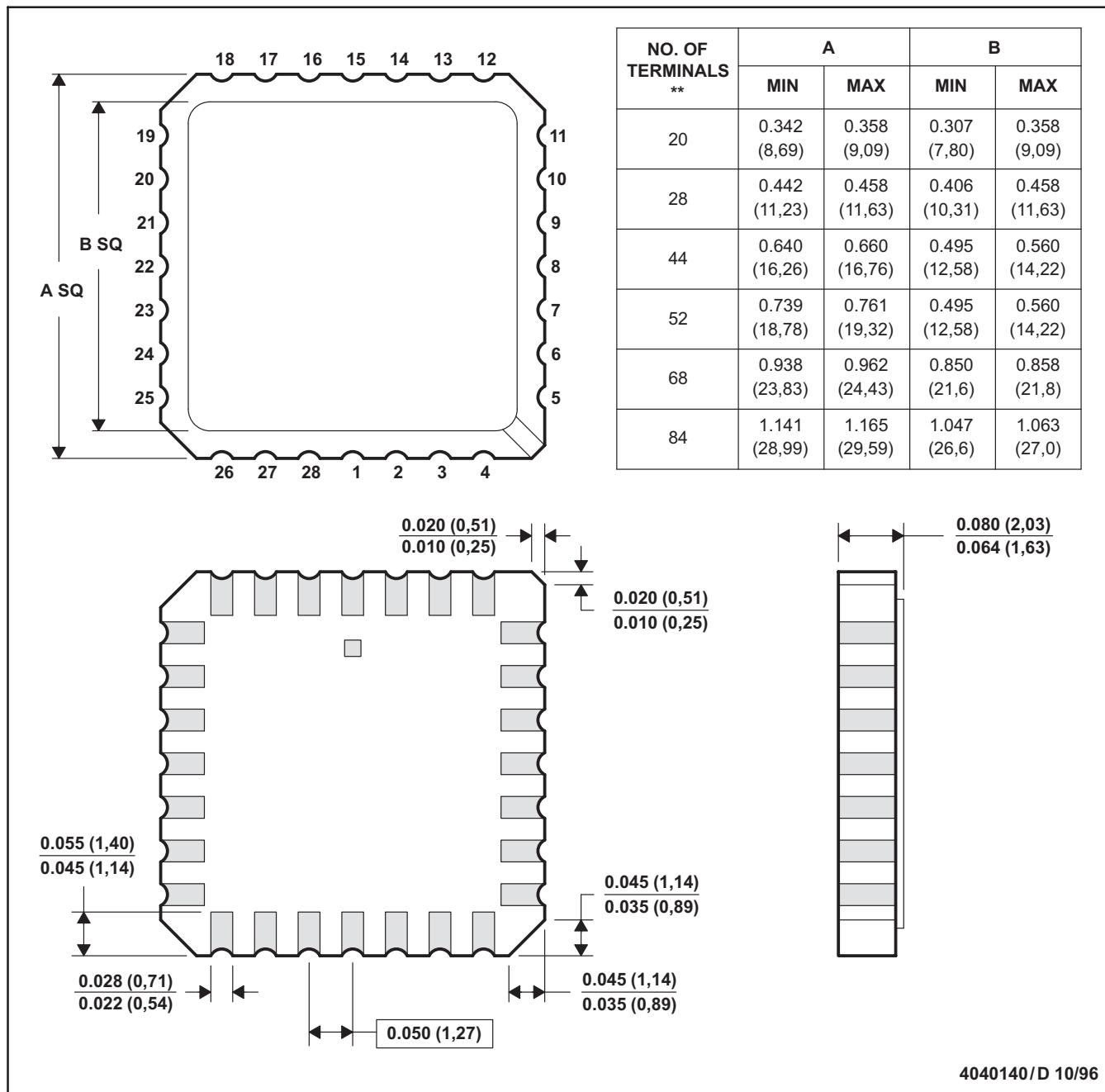
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL-STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



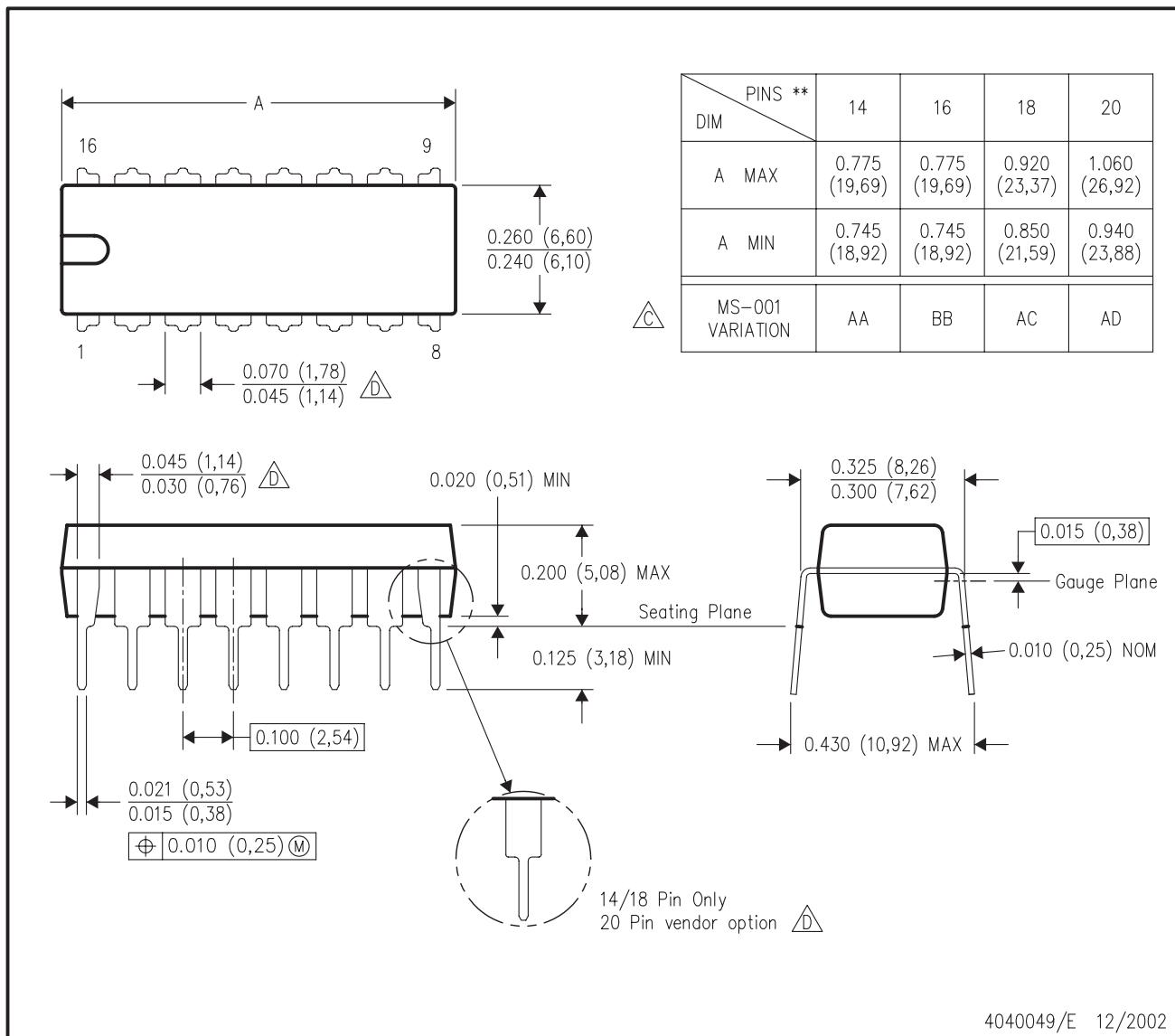
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



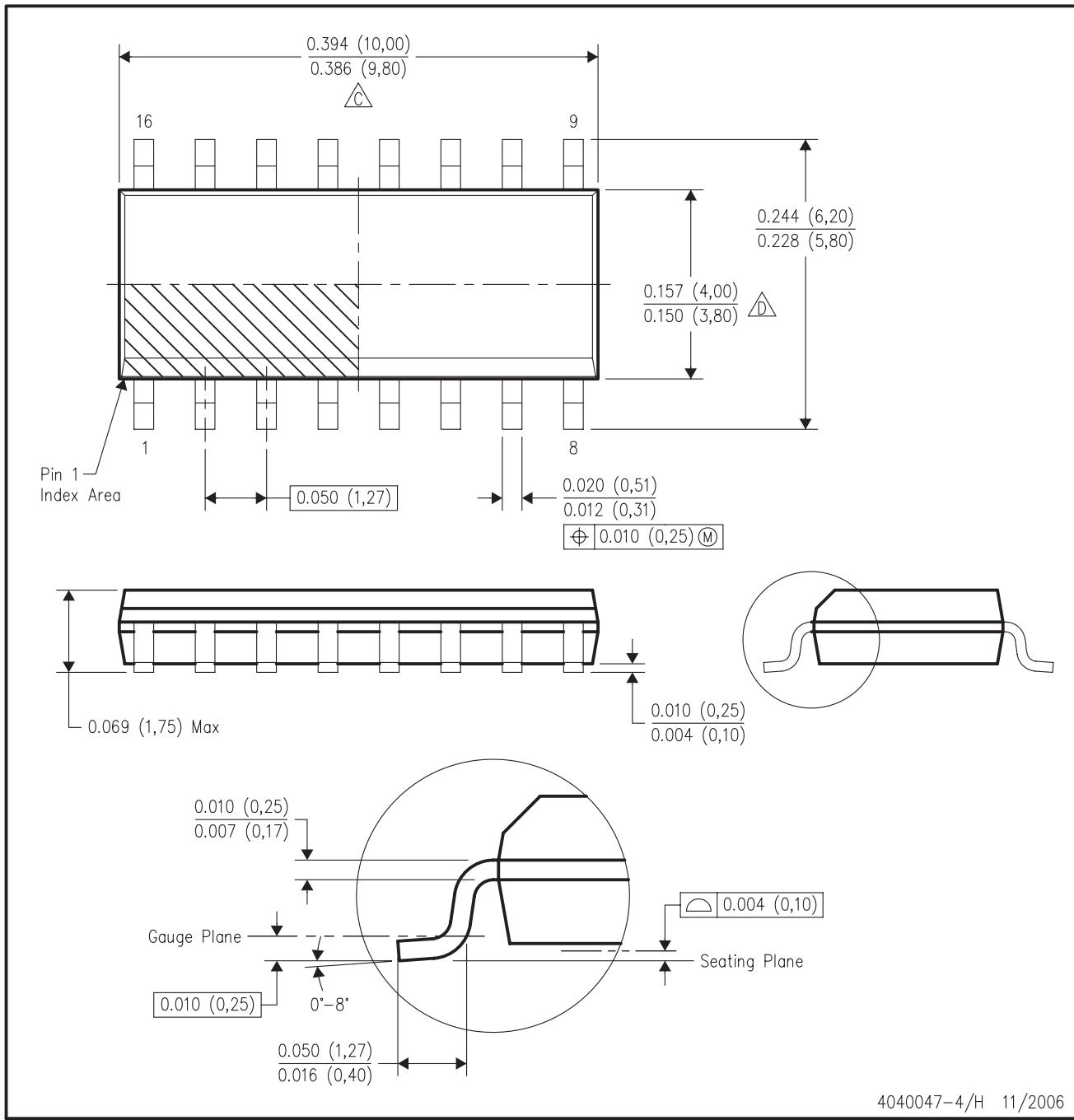
NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

△ C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ D The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/H 11/2006

NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

△C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

△D Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

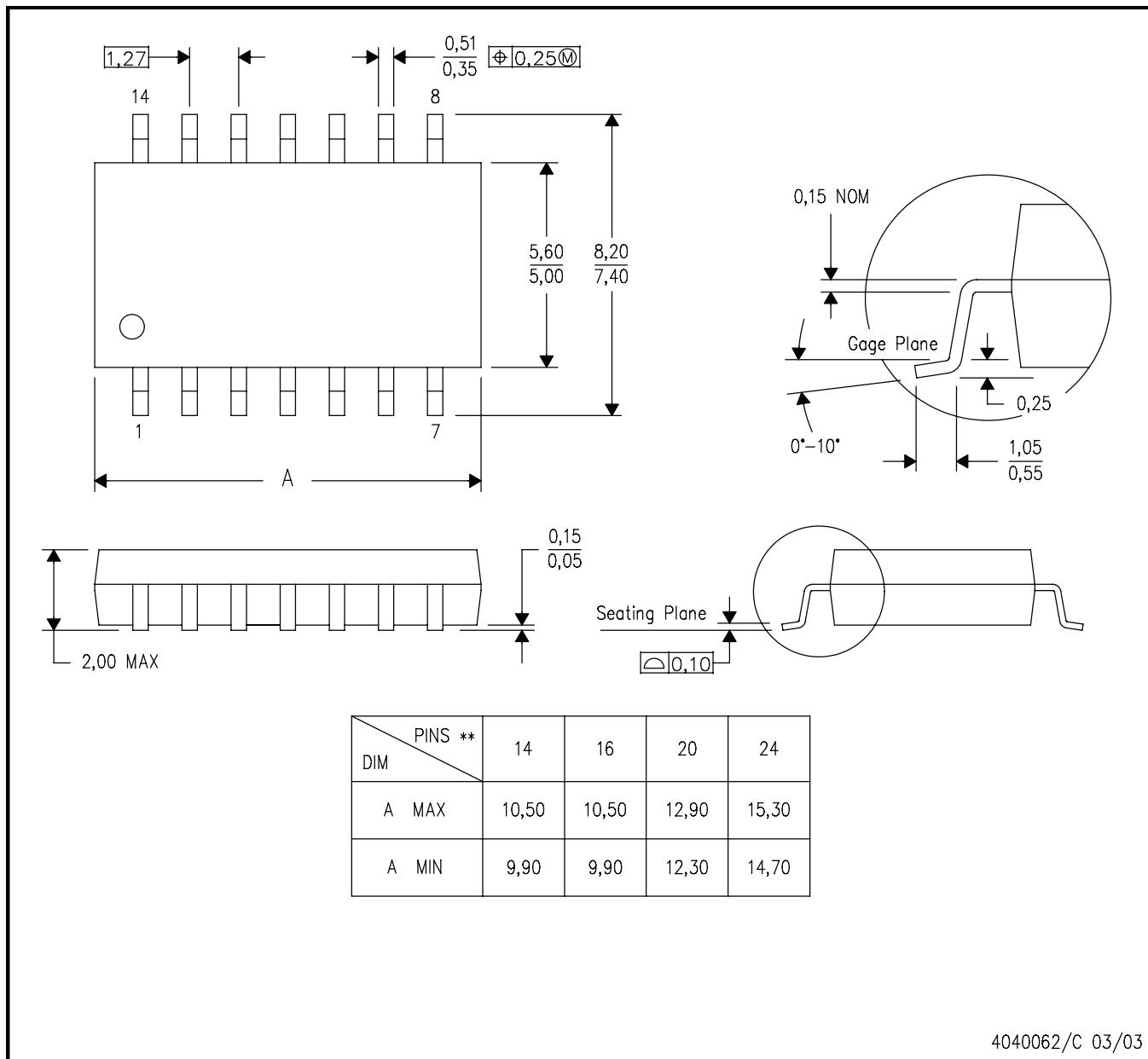
E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-87517012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8751701EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8751701EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8751701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-8751701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74LS590D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590N3	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SN74LS590N3	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SN74LS590NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS590FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS590FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS590W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS590W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

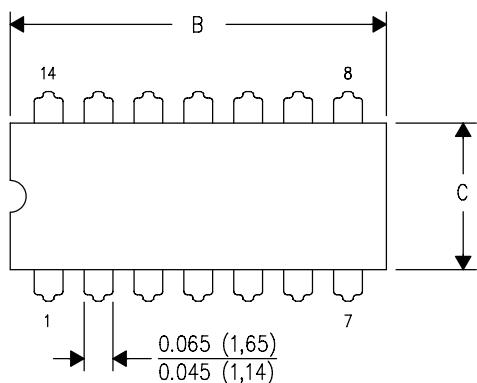
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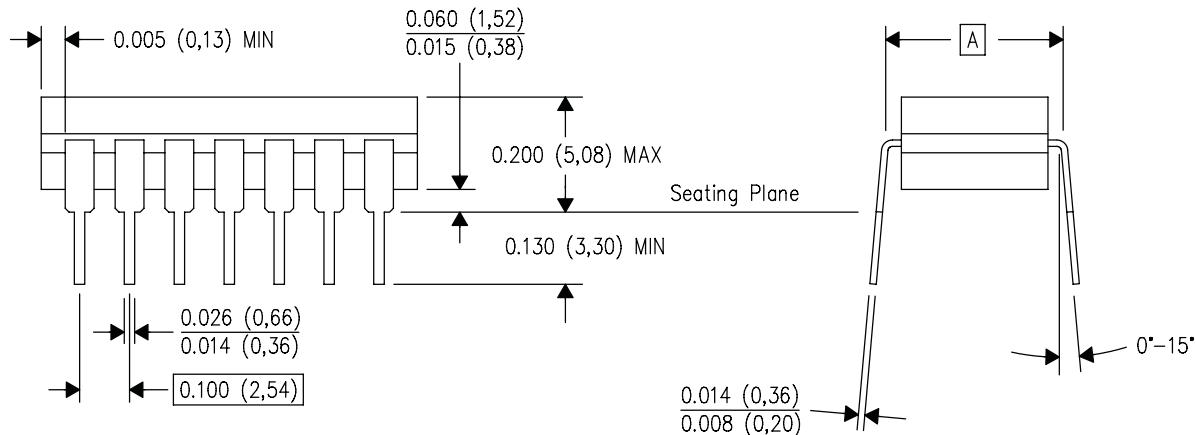
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

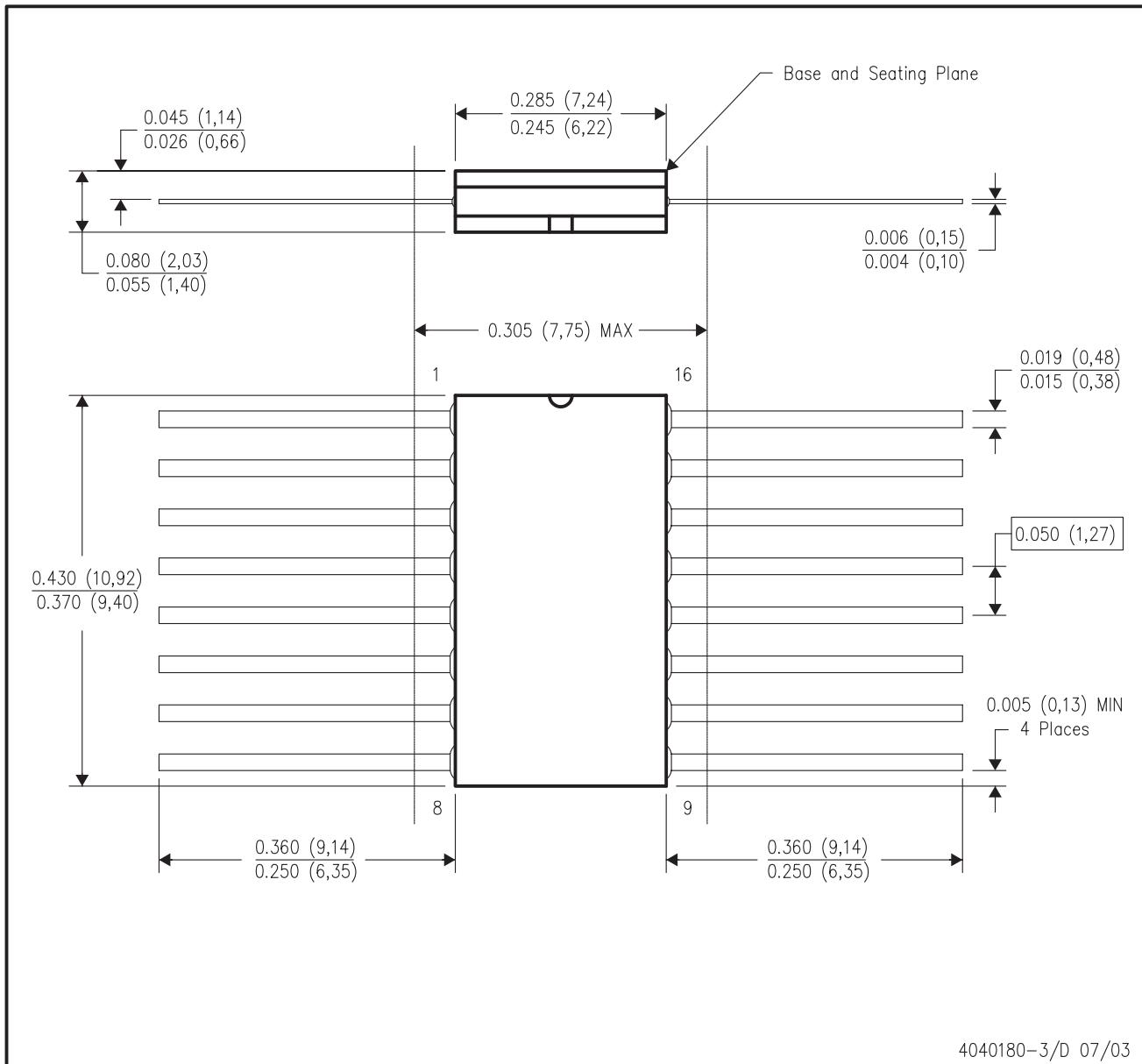


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



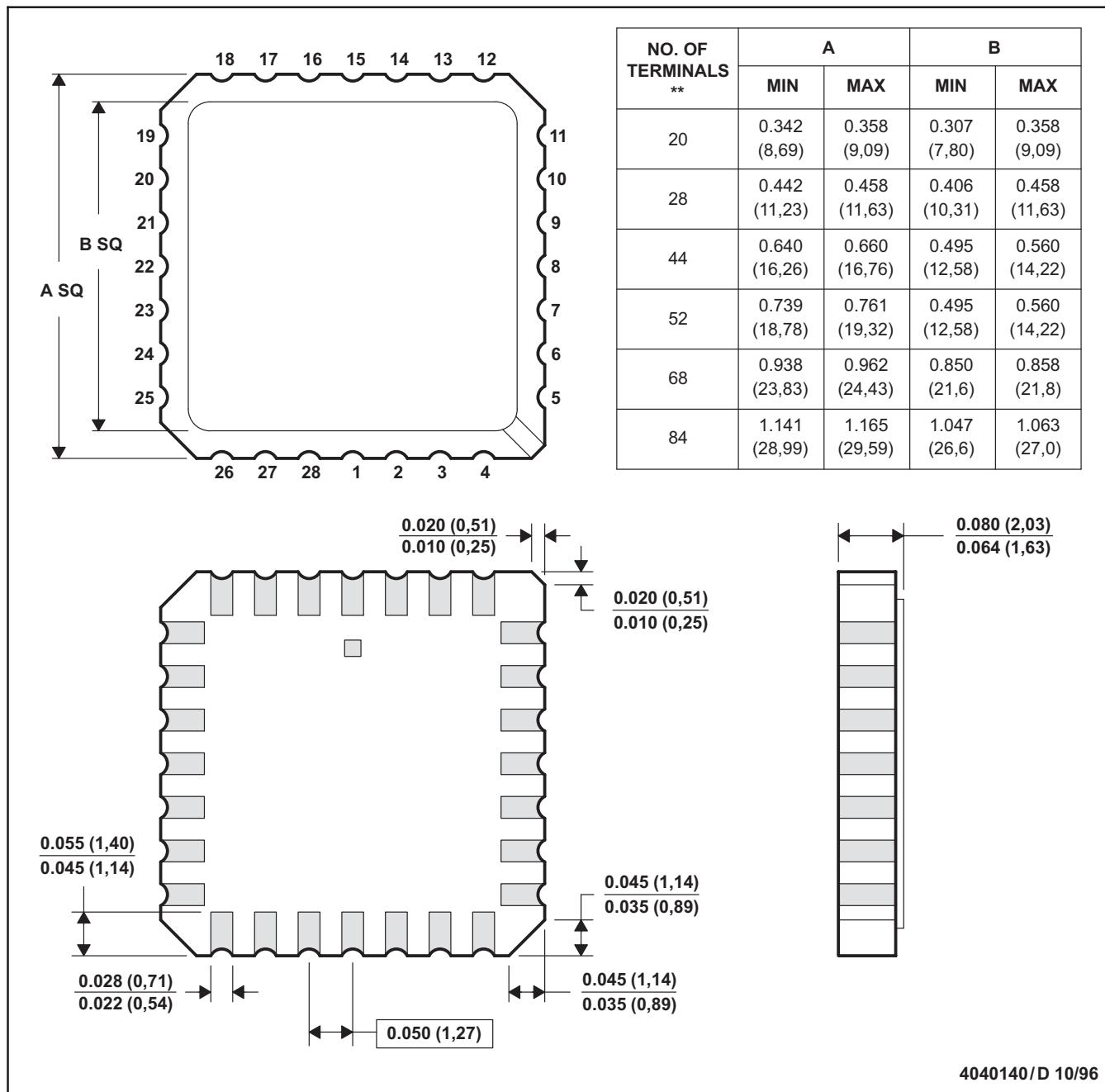
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL-STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. The terminals are gold plated.

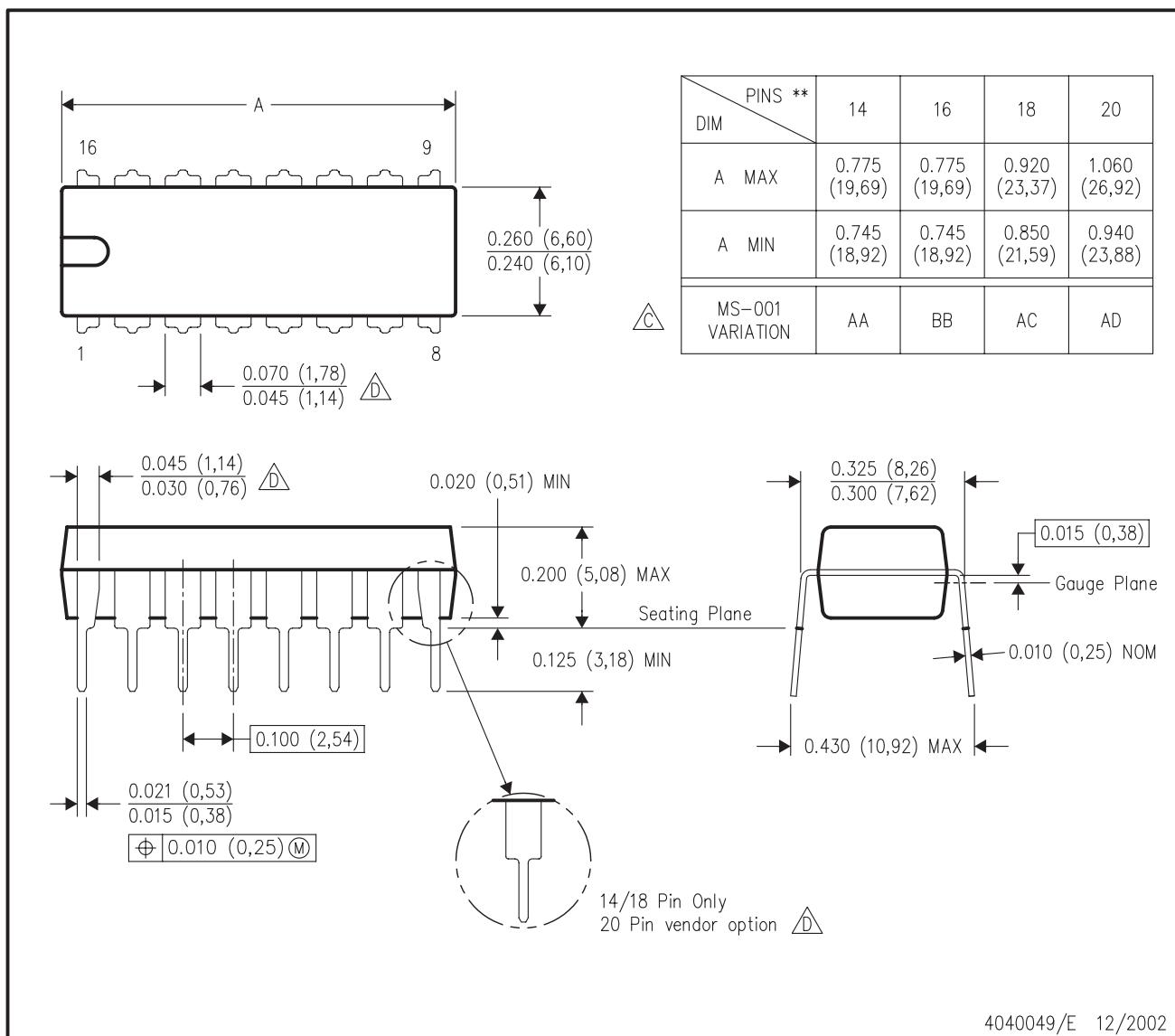
E. Falls within JEDEC MS-004

4040140/D 10/96

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



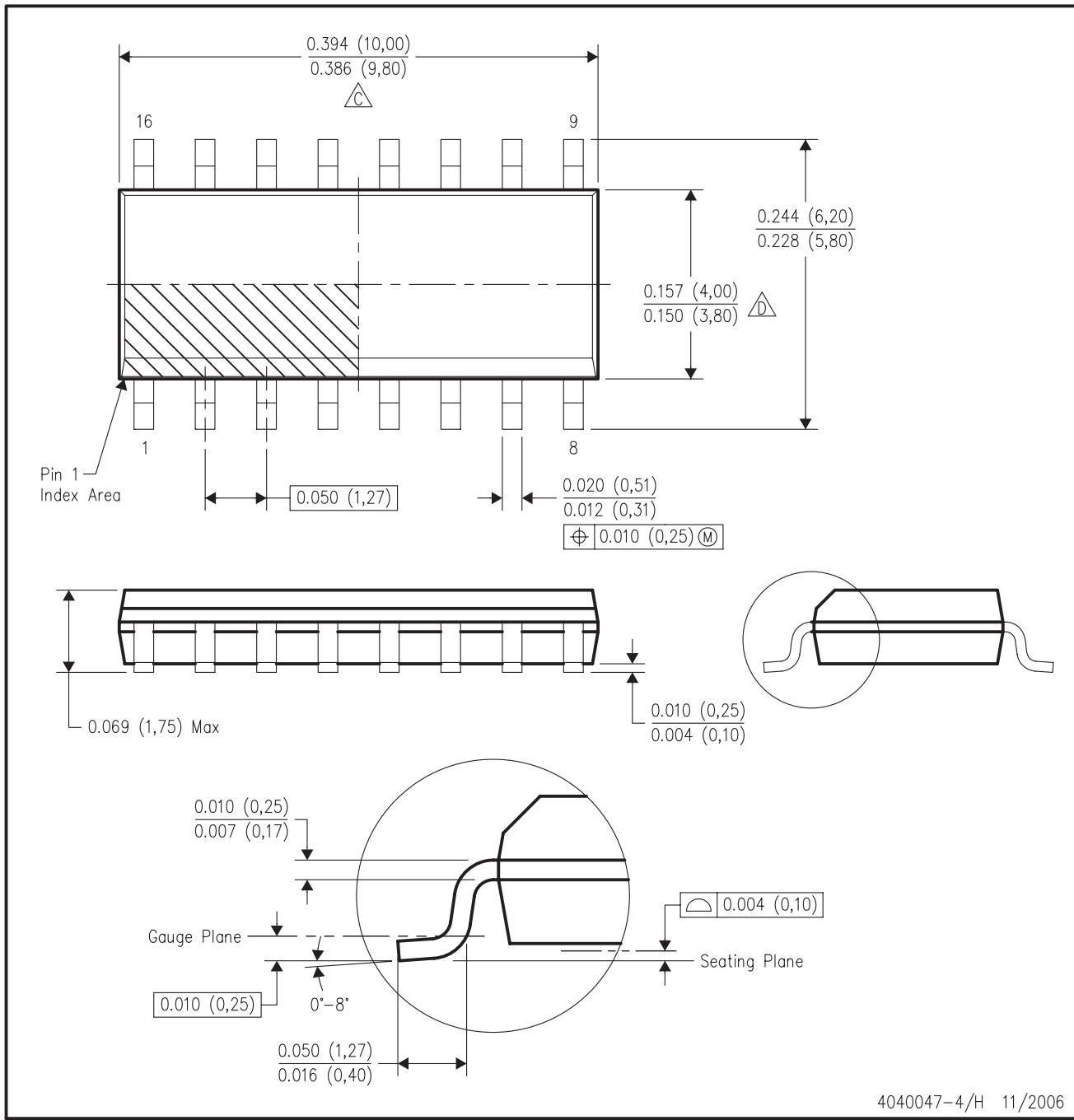
NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

△ C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ D The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/H 11/2006

NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

△C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

△D Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

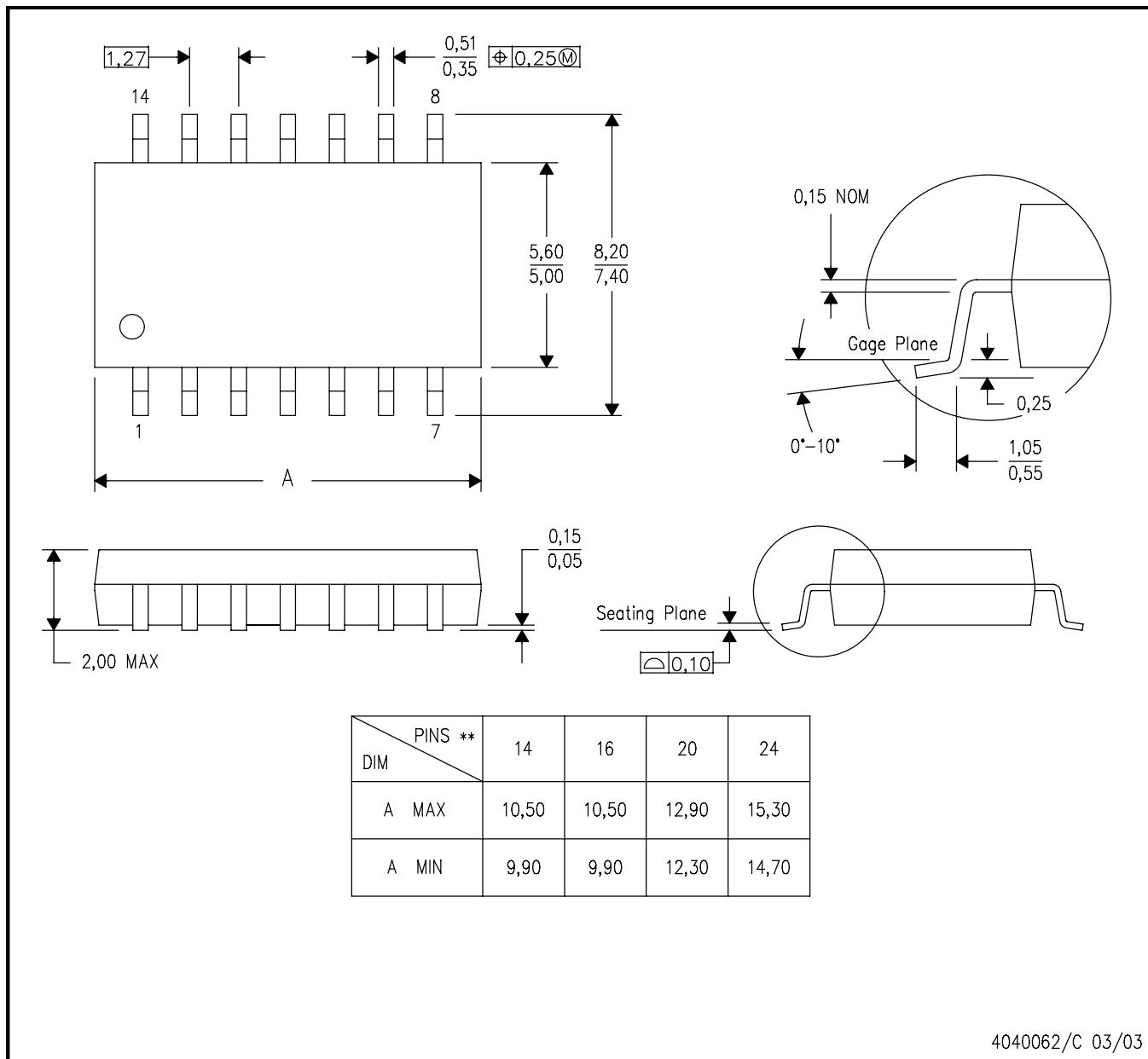
E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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